

- 產品特性 -

重量輕
接觸空氣散熱面大
高導熱效能
表面抗組高
高耐電壓值
適合用於小型設備

- Product Features -

Low weight
Big air-contact area
Good heat spreader
High Resistance
High Voltage Breakdown
Suitable for small devices

- 應用範圍 -

功率晶體管
功率模塊
中央處理器
晶片集成電路
印刷電路板

- Application Area -

Power Transistor
Power Module
CPU
Chip IC
PC Board

料號	P/N	CH-22	Unit	Test Method
顏色	Color	Green	---	Visual
尺寸規格	Dimensions	(See page 17)	mm	---
導熱係數	Thermal conductivity	7.2	W/mk	---
比重	Specific Gravity	1.85±0.2	g/cm ³	ASTM D792
表面阻抗	Surface Resistivity	>110	ohm	ASTM D257
彎曲強度	Flexural strength	48	Kgf/cm ²	CNS12701
孔隙度	Porosity	30	%	CNS619
硬度	Hardness	5±1	Moh's	DIN En101-1992
熱膨脹係數	Coefficient of Thermal Expansion	4.1	10 ⁻⁶	RT-300C
耐電壓	Dielectric Strength	>5	KV	ASTM D149
耐溫範圍	Temp Range	< 500	°C	---
主要成分	Composition	Sic / SiO ₂	---	---

- 建議儲存在常溫常濕環境中。 Store at room temperature and humidity conditions.
- 若需要非常規尺寸，請聯繫業務員。 Contact sales for custom sizes.
- 常規形狀包括平板和波浪形狀（見下圖）。 Standard shapes: flat, wave surface (see below).



- 正反面都是平面，可加背膠使用。
- Both sides are flat and adhesive-compatible.



- 正面是波浪狀，另一面是平面狀，平面那端可以加背膠。
- One side is wavy, the other side is flat, and the flat side can be adhesive-backed.

- CH-22 常規品請參閱以下 -

- Please refer to the following for standard products CH-22. -

Length * Width * Thickness (mm)
(F) = Flat Surface (W) = Wave Surface



以上技術資料為檢驗的平均數據。請根據您的實際使用情況選擇適合的產品，最終決定應基於您的試用結果。

The above technical data represents the average results obtained from inspections. Please choose products based on your actual usage conditions. The final decision should rely on your trial results.